

### Typical Applications

The HMC424LH5 is ideal for:

- Telecom Infrastructure
- Military Radio, Radar & ECM
- Space Systems
- Test Instrumentation

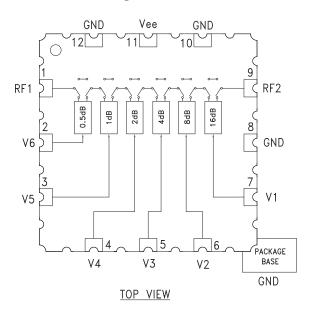
#### **Features**

0.5 dB LSB Steps to 31.5 dB Single Control Line Per Bit ± 0.3 dB Typical Bit Error

Hermetic SMT Package, 25mm<sup>2</sup>

Screening to MIL-PRF-38535 (Class B or S) Available

### **Functional Diagram**



#### **General Description**

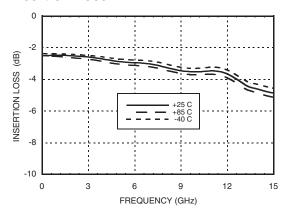
The HMC424LH5 is a broadband 6-bit GaAs MMIC digital attenuator housed in a hermetic SMT leadless package. Covering DC to 13 GHz, the insertion loss is less than 3.5 dB typical. The attenuator bit values are 0.5 (LSB), 1, 2, 4, 8, and 16 dB for a total attenuation of 31.5 dB. Attenuation accuracy is excellent at ±0.5 dB typical step error with an IIP3 of +32 dBm. Six control voltage inputs, toggled between 0 and -5V, are used to select each attenuation state. A single Vee bias of -5V allows operation at frequencies down to DC. The HMC424LH5 is compatible with standard and lead free surface mount manufacturing techniques and is suitable for high reliability military, industrial and space applications.

## Electrical Specifications, $T_A = +25^{\circ}$ C, With Vee = -5V & VCTL= 0/-5V

Parameter		Frequency (GHz)	Min.	Тур.	Max.	Units
Insertion Loss		DC - 4 GHz 4.0 - 8.0 GHz 8.0 - 13.0 GHz		2.7 3.3 4.2	3.2 3.8 4.7	dB dB dB
Attenuation Range		DC - 13.0 GHz		31.5		dB
Return Loss (RF1 & RF2, All Atten. States)		DC - 13.0 GHz		12		dB
Attenuation Accuracy: (Referenced to Insertion Loss)	0.5 - 16.5 dB States 17 - 31.5 dB States	DC - 13.0 GHz DC - 13.0 GHz	± 0.4 + 4% of Atten. Setting Max ± 0.5 + 5% of Atten. Setting Max		dB dB	
Input Power for 0.1 dB Compression		1.0 - 13.0 GHz		22		dBm
Input Third Order Intercept Point (Two-Tone Input Power= 0 dBm Each Tone)	REF State All Other States	1.0 - 13.0 GHz		46 32		dBm dBm
Switching Characteristics		DC - 13.0 GHz				
tRISE, tFALL (10/90% RF) tON/tOFF (50% CTL to 10/90% RF)				30 50		ns ns

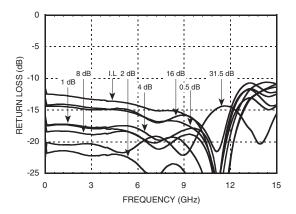


#### **Insertion Loss**



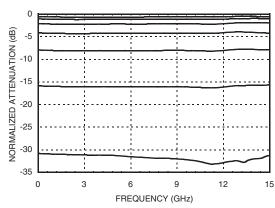
### Return Loss RF1, RF2

(Only Major States are Shown)

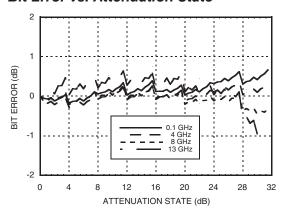


#### **Normalized Attenuation**

(Only Major States are Shown)

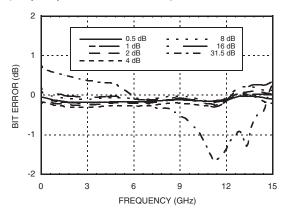


#### Bit Error vs. Attenuation State



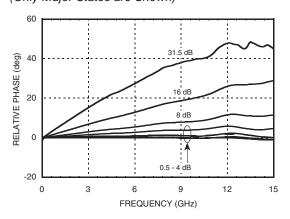
#### Bit Error vs. Frequency

(Only Major States are Shown)



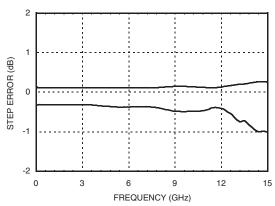
#### Relative Phase vs. Frequency

(Only Major States are Shown)





#### Worst Case Step Error Between Successive Attenuation States



#### Bias Voltage & Current

Vee Range= -5 Vdc ± 10%			
Vee (VDC)	lee (Typ.) (mA)	lee (Max.) (mA)	
-5.0	3	5	

#### **Control Voltage**

State	Bias Condition
Low	0 to -3V @ 35 μA Typ.
High	Vee to Vee +0.8V @ 5 μA Typ.

#### **Truth Table**

Control Voltage Input					Attenuation		
V1 16 dB	V2 8 dB	V3 4 dB	V4 2 dB	V5 1 dB	V6 0.5 dB	State RF1 - RF2	
Low	Low	Low	Low	Low	Low	Reference I.L.	
Low	Low	Low	Low	Low	High	0.5 dB	
Low	Low	Low	Low	High	Low	1 dB	
Low	Low	Low	High	Low	Low	2 dB	
Low	Low	High	Low	Low	Low	4 dB	
Low	High	Low	Low	Low	Low	8 dB	
High	Low	Low	Low	Low	Low	16 dB	
High	High	High	High	High	High	31.5 dB	

Any Combination of the above states will provide an attenuation approximately equal to the sum of the bits selected.

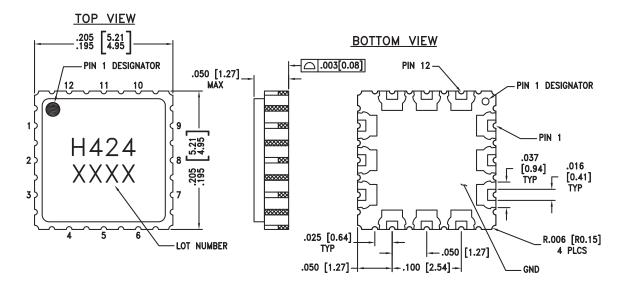


### **Absolute Maximum Ratings**

Control Voltage (V1 to V6)	Vee - 0.5 Vdc
Bias Voltage (Vee)	-7 Vdc
Channel Temperature	150 °C
Thermal Resistance	344 °C/W
Continuous Pdiss (T= 85 °C) (derate 2.9 mW/ °C above 85 °C)	0.18 W
Storage Temperature	-65 to + 150 °C
Operating Temperature	-40 to +85 °C
RF Input Power (0.5 - 13 GHz)	+25 dBm



### **Outline Drawing**



#### NOTES:

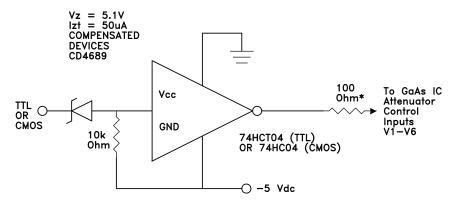
- 1. PACKAGE BODY MATERIAL: CERAMIC & KOVAR
- 2. LEAD AND GROUND PADDLE PLATING: GOLD 40 80 MICROINCHES.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- PAD BURR LENGTH 0.15mm MAX. PAD BURR HEIGHT 0.25mm MAX.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.



### Pin Description

Pad Number	Function	Description	Interface Schematic
1, 9	RF1, RF2	This pin is DC coupled and matched to 50 Ohm. Blocking capacitors are required if RF line potential is not equal to 0V.	
2 - 7	V6 - V1	See truth table and control voltage table.	100K Vee
8, 10, 12	GND	Package base must also be connected to RF ground	⊖ GND =
11	Vee	Supply Voltage -5V ± 10%	

## Suggested Driver Circuit (One Circuit Required Per Bit Control Input)

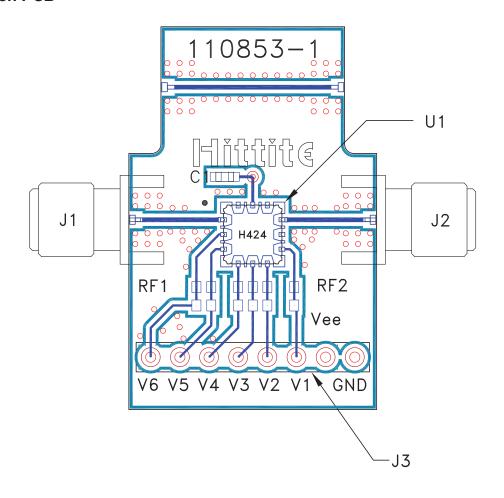


Simple driver using inexpensive standard logic ICs provides fast switching using minimum DC current.

- \* Recommended value to suppress unwanted RF signals at V1
- V6 control lines.



#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 110855 [1]

Item	Description
J1 - J2	PCB Mount SMA SRI Connector
J3	8 Pin DC Connector .1" Thruhole
C1	0.01 μF Capacitor, 0603 Pkg.
U1	HMC424LH5 Digital Attenuator
PCB [2]	110853 Evaluation PCB

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350